

Features

- 68W (8/20 μ s) Peak Pulse Power
- Low Capacitance ESD Protection
- SOD - 923 Package
- RoHS Compliant
- Matte Tin Lead finish (Pb-Free)
- Protect One High Speed Data Line
- Meet IEC61000-4-2 Level 4:
Contact Discharge > 20kV Air
Discharge > 20kV

Applications

- Communication System
- Portable Instrumentation
- Audio and Video Equipment
- Computers and Peripherals
- USB 1.1, USB 1.0 Ports

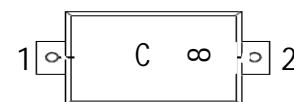
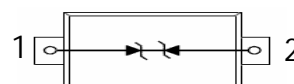
Ordering information

Type No.	Marking	Package Code
LXE5V015PB9	C8	SOD-923

Circuit Diagram



SOD-923



Marking

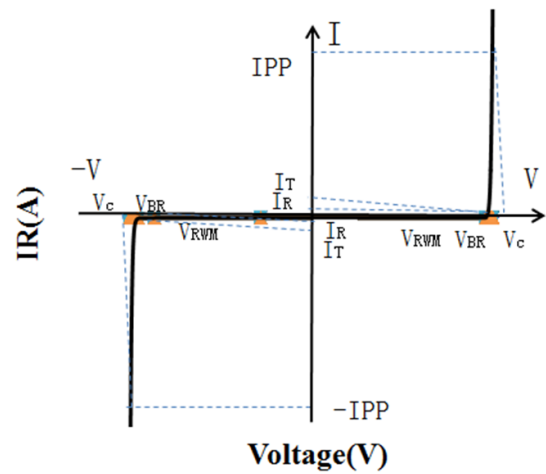
C= Device Code
8 = Date Code*

Maximum Ratings (Ta = 25°C)

Symbol	Parameter	Value	Unit
P _{PK}	Peak Pulse Power	68	W
I _{PP}	Peak Pulse Current	5.5	A
V _{ESD (Contact)}	Contact ESD Voltage per IEC61000-4-2	20	kV
V _{ESD (Air)}	Air ESD Voltage per IEC61000-4-2	20	kV
T _J	Junction Temperature	-55 to +150	°C
T _{STG}	Storage Temperature	-55 to +150	°C

Portion Electronics Parameter

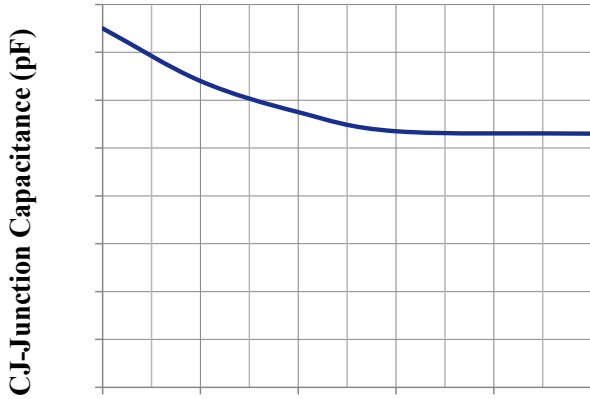
Symbol	Parameter
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @Ic



Electrical Characteristics (Ta = 25°C)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RWM}	Reverse Working Peak Voltage				5	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1\text{mA}$	5.7		9	V
I_R	Reverse Leakage Current	$V_{RWM} = 5\text{V}$			0.1	μA
V_C	Clamping Voltage	$I_{PP} = 1\text{A} (8/20\mu\text{s})$			12	V
V_C	Clamping Voltage	$I_{PP} = 5.5\text{A} (8/20 \mu\text{s})$			17	V
C_J	Capacitance	$V_R = 0\text{V}, f = 1\text{MHz}$	8	8.9	15	pF

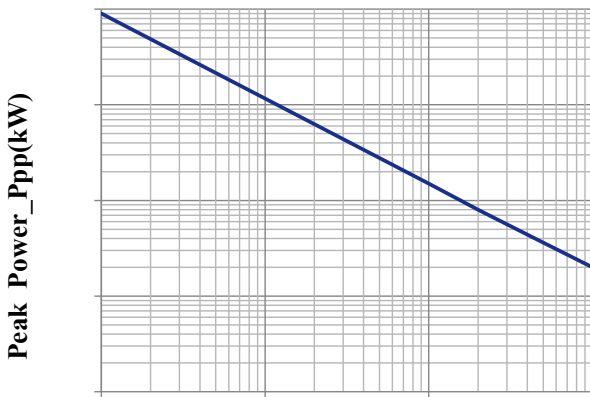
Typical Performance Characteristics (TA=25°C unless otherwise Specified)



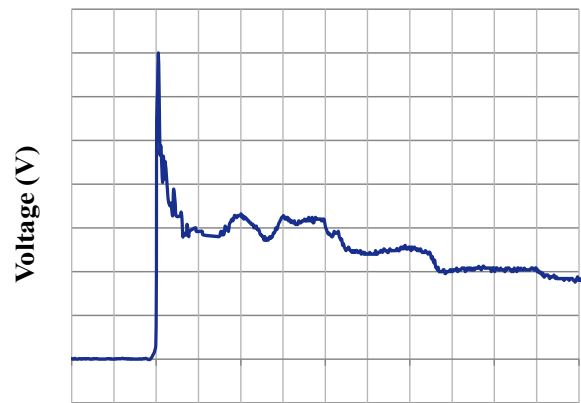
VR—Reverse Voltage(V)
Junction Capacitance vs. Reverse Voltage



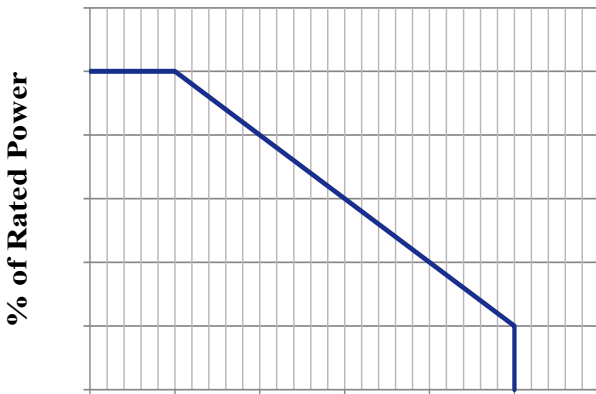
Ipp-Peak Pulse Current(A)
Clamping Voltage vs. Peak Pulse Current



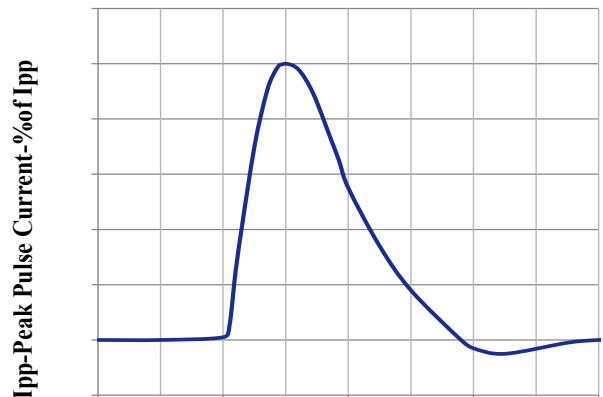
Pulse Duration_tp(uS)
Peak Pulse Power vs. Pulse Time



Time (nS)
IEC61000 Pulse Waveform

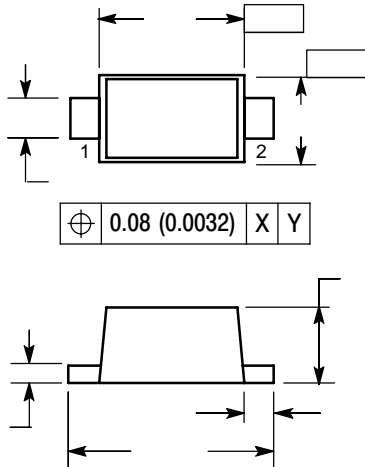


Ambient Temperature_Ta(°C)
Power Derating Curve



T-Time(us)
8 X 20us Pulse Waveform

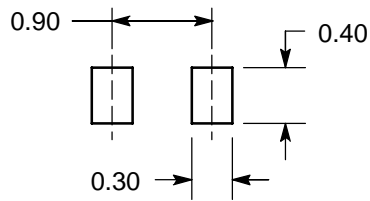
SOD-923



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS